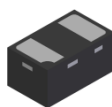


## Features

- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **The DIODES™ BZT52C6V8LPQ - BZT52C16LPQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF16949 certified facilities.**  
<https://www.diodes.com/quality/product-definitions/>

## Mechanical Data

- Package: X1-DFN1006-2
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Marking Information
- Terminals: Finish—NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.001 grams (Approximate)



Bottom View

## Ordering Information (Note 4)

Part Number	Package	Packing	
		Qty.	Carrier
(Type Number)-7*	X1-DFN1006-2	3,000	Tape & Reel
(Type Number)-7B**	X1-DFN1006-2	10,000	Tape & Reel

\*Add "-7" to the appropriate type number in Electrical Characteristics Table. Example: 13V Zener = BZT52C13LPQ-7.

\*\*Add "-7B" to the appropriate type number in Electrical Characteristics Table. Example: 13V Zener = BZT52C13LPQ-7B.

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



Top View  
Bar Denotes  
Cathode Side

xx = Product Type Marking Code  
(See Electrical Characteristics Table)

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Forward Voltage (Note 5) @ I <sub>F</sub> = 10mA	V <sub>F</sub>	0.9	V

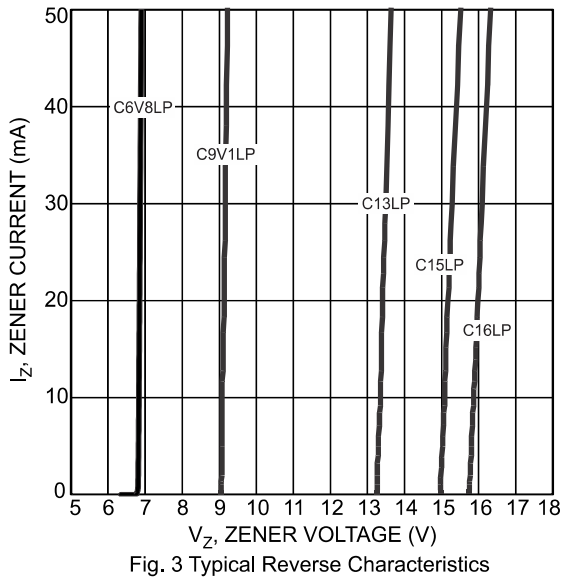
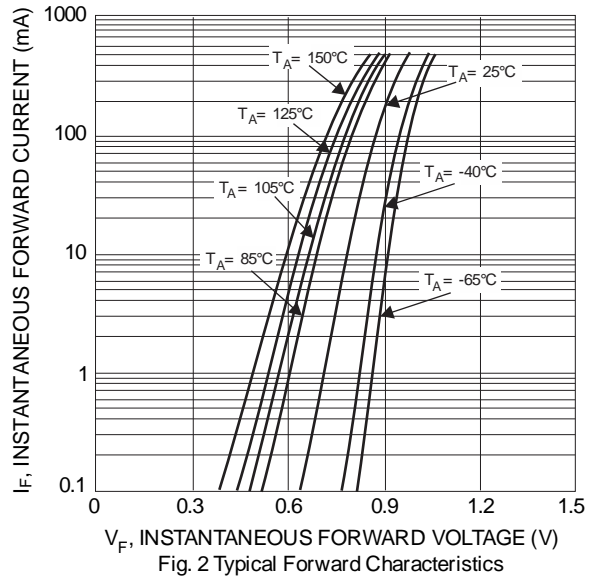
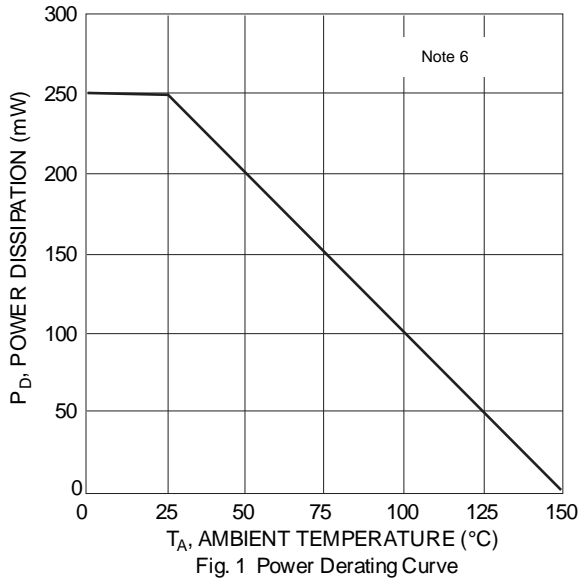
**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6) T <sub>A</sub> = +25°C	P <sub>D</sub>	250	mW
Thermal Resistance, Junction to Ambient Air (Note 6) T <sub>A</sub> = +25°C	R <sub>θJA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Type Number	Marking Code	Zener Voltage Range (Note 5)				Maximum Zener Impedance f = 1kHz			Maximum Reverse Current (Note 5)		Temperature Coefficient @ I <sub>ZTC</sub> mV/°C		Test Current I <sub>ZTC</sub> mA
		V <sub>Z</sub> @ I <sub>ZT</sub>			I <sub>ZT</sub>	Z <sub>ZT</sub> @ I <sub>ZT</sub>	Z <sub>ZK</sub> @ I <sub>ZK</sub>	I <sub>ZK</sub>	I <sub>R</sub>	@ V <sub>R</sub>	Min	Max	
		Nom (V)	Min (V)	Max (V)	mA	Ω	mA	μA	V				
BZT52C6V8LPQ	9C	6.8	6.4	7.2	5	15	80	1.0	2.0	4.0	1.2	4.5	5
BZT52C9V1LPQ	9F	9.1	8.5	9.6	5	15	100	1.0	0.5	6.0	3.8	7.0	5
BZT52C13LPQ	9K	13	12.4	14.1	5	30	170	1.0	0.1	8.0	7.0	11.0	5
BZT52C15LPQ	9L	15	13.8	15.6	5	30	200	1.0	0.1	10.5	9.2	13.0	5
BZT52C16LPQ	9M	16	15.3	17.1	5	40	200	1.0	0.1	11.2	10.4	14.0	5

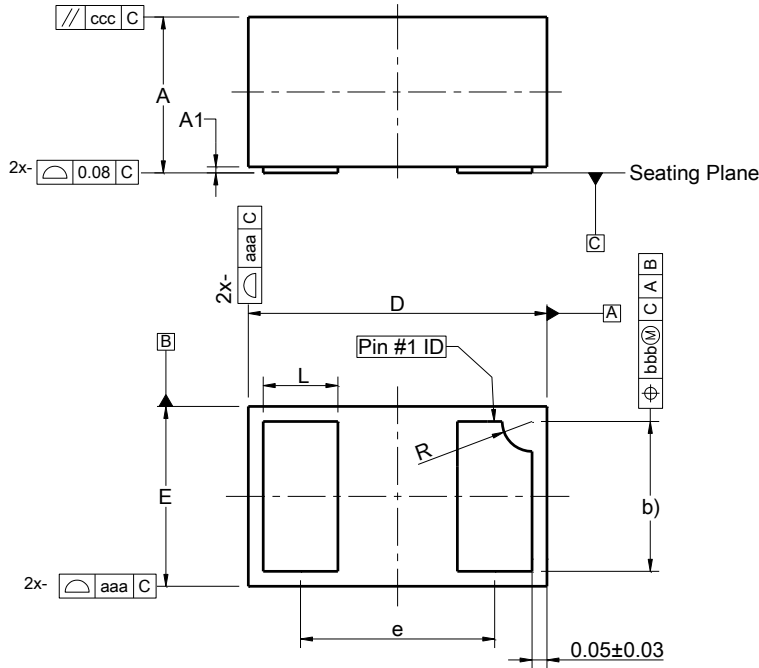
- Notes:
5. Short duration pulse test used to minimize self-heating effect.
  6. Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found at <http://www.diodes.com/package-outlines.html>.



**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-2**

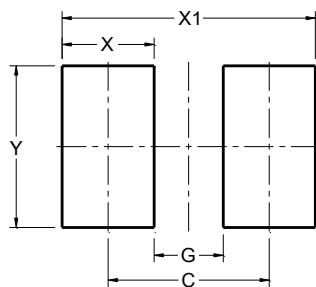


X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	--	--	0.65
L	0.20	0.30	0.25
R	0.05	0.15	0.10
aaa	0.15		
bbb	0.05		
ccc	0.05		
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-2**



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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